## **CLAIMS**

1. A substrate for a semiconductor device, on which a circuit component can be mounted, characterized in,

that a surface opposite to an element mounting surface is counterbored so as to form a component mounting hole where a connection terminal, which will be electrically connected to the circuit component, is exposed in the inner bottom face.

- 2. The substrate according to claim 1, wherein the component mounting hole is located in a semiconductor element mounting area.
- 3. The substrate according to claim 2, wherein the circuit component, which is electrically connected to the connection terminal, is mounted in the component mounting hole.
- 4. A semiconductor device comprising: the substrate of claim 3; and a semiconductor element being mounted on the substrate by flip-chip connection.
- 5. The substrate according to claim 1, wherein the substrate is constituted by a core plate and a cable layer or layers formed on the core plate, and

the surface of the substrate, which is opposite to the element mounting surface thereof, is counterbored so as to form a component mounting hole where a connection terminal, which is formed in the cable layer, is exposed in the inner bottom face.

- 6. The substrate according to claim 5, wherein the component mounting hole is located in a semiconductor element mounting area.
- 7. The substrate according to claim 6, wherein the circuit component, which is electrically connected to the connection terminal, is mounted in the component mounting hole.
- 8. The substrate according to claim 7, wherein a decoupling capacitor

is mounted as the circuit component.

9. A semiconductor device comprising: the substrate of claim 7 or 8; and a semiconductor element being mounted on the substrate by flip-chip connection.